



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSC007N04LS6	<b>Issued</b>	13. April 2021
<b>MA#</b>	MA004017256		
<b>Package</b>	PG-TDSON-8-35	<b>Weight*</b>	115.26 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.091	1.81	1.81	18143	18143
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		135	
	non noble metal	iron	7439-89-6	0.052	0.04		449	
	non noble metal	copper	7440-50-8	51.740	44.91	44.96	448901	449485
wire	noble metal	gold	7440-57-5	0.034	0.03	0.03	295	295
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		695	
	plastics	epoxy resin	-	6.324	5.49		54867	
	inorganic material	silicon dioxide	60676-86-0	33.621	29.17	34.73	291698	347260
leadfinish	non noble metal	tin	7440-31-5	1.392	1.21	1.21	12073	12073
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1682	1682
solder	non noble metal	tin	7440-31-5	0.051	0.04		445	
	noble metal	silver	7440-22-4	0.064	0.06		556	
	non noble metal	lead	7439-92-1	2.448	2.12	2.22	21235	22236
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	17.131	14.86	14.87	148632	148826
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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